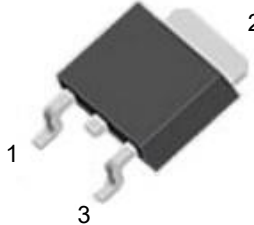
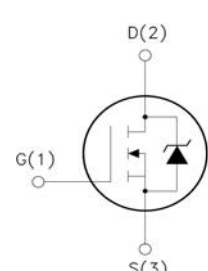


<h2 style="margin: 0;">CTKD5N50SE</h2> <p>Features:</p> <ul style="list-style-type: none"> <input type="checkbox"/> Low Intrinsic Capacitances. <input type="checkbox"/> Excellent Switching Characteristics. <input type="checkbox"/> Extended Safe Operating Area. <input type="checkbox"/> Unrivalled Gate Charge :Qg=13nC (Typ.). <input type="checkbox"/> V_{DSS}=500V, I_D=5A <input type="checkbox"/> R_{DS(on)} : 1.4Ω (Max) @V_G=10V <input type="checkbox"/> 100% Avalanche Tested 	<h2 style="margin: 0;">TO-252</h2> <div style="text-align: center;">  </div> <div style="text-align: center;">  </div> <div style="margin-top: 10px;"> <p>1.Gate (G) 2.Drain (D) 3.Source (S)</p> </div>
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Absolute Maximum Ratings (Ta=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{DSS}	Drain-Source Voltage	500	V
I _D	Drain Current	T _j =25°C	A
		T _j =100°C	
V _{GSS}	Gate-Source Voltage	±30	V
E _{AS}	Single Pulse Avalanche Energy (note1)	270	mJ
I _{AR}	Avalanche Current (note2)	5.0	A
P _D	Power Dissipation (T _j =25°C)	25	W
T _j	Junction Temperature(Max)	150	°C
T _{stg}	Storage Temperature	-55~+150	°C
TL	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJC}	Thermal Resistance, Junction to Case	-	3.45	°C/W
R _{θJA}	Thermal Resistance, Junction to Ambient	-	110	°C/W

Electrical Characteristics (Ta=25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0	500	-	-	V
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temperature Coefficient	I _D =250μA, Reference to 25°C	-	0.47	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =500V, V _{GS} =0V	-	-	1	μA
		V _{DS} =400V, T _J =125°C	-	-	10	
I _{GSSF}	Gate-body leakage Current, Forward	V _{GS} =+30V, V _{DS} =0V	-	-	100	nA
I _{GSSR}	Gate-body leakage Current, Reverse	V _{GS} =-30V, V _{DS} =0V	-	-	-100	
On Characteristics						
V _{GS(TH)}	Date Threshold Voltage	I _D =250μA, V _{DS} =V _{GS}	2	-	4	V
R _{DS(ON)}	Static Drain-Source On-Resistance	I _D =2.5A, V _{GS} =10V	-	-	1.4	Ω
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0, f=1.0MHz	-	620	-	pF
C _{oss}	Output Capacitance		-	70	-	
C _{rss}	Reverse Transfer Capacitance		-	8	-	
Switching Characteristics						
T _{d(on)}	Turn-On Delay Time	V _{DD} =250V, I _D =5A R _G =25Ω (Note 3,4)	-	13	35	ns
T _r	Turn-On Rise Time		-	55	120	
T _{d(off)}	Turn-Off Delay Time		-	25	60	
T _f	Turn-Off Rise Time		-	35	80	
Q _g	Total Gate Charge	V _{DS} =400V, V _{GS} =10V, I _D =5A (Note 3,4)	-	13	17	nC
Q _{gs}	Gate-Source Charge		-	3.4	-	
Q _{gd}	Gate-Drain Charge		-	6.4	-	
Drain-Source Diode Characteristics and Maximum Ratings						
I _s	Max. Diode Forward Current	-	-	-	5.0	A
I _{SM}	Max. Pulsed Forward Current	-	-	-	20	
V _{SD}	Diode Forward Voltage	I _D =5A	-	-	1.5	V
T _{rr}	Reverse Recovery Time	I _S =5A, V _{GS} =0V diF/dt=100A/μs	-	215	-	nS
Q _{rr}	Reverse Recovery Charge	(Note3)	-	1.26	-	μC

- Notes : 1, L=27mH, I_{AS}=5A, V_{DD}=50V, R_G=25Ω, Starting T_J=25°C
 2, Repetitive Rating : Pulse width limited by maximum junction temperature
 3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%
 4, Essentially Independent of Operating Temperature

Typical Characteristics

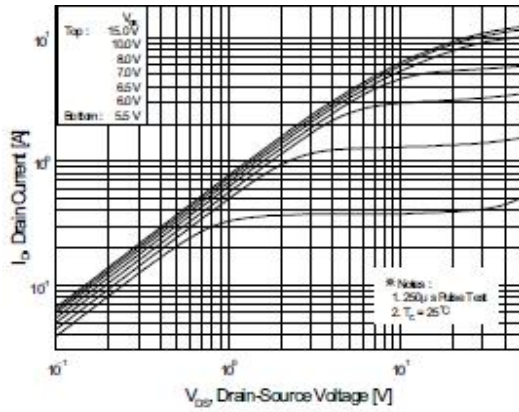


Figure 1. On-Region Characteristics

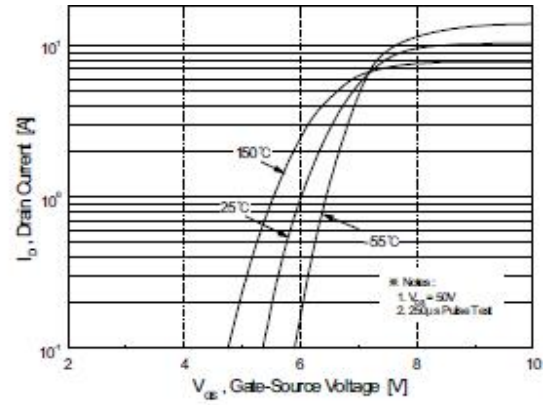


Figure 2. Transfer Characteristics

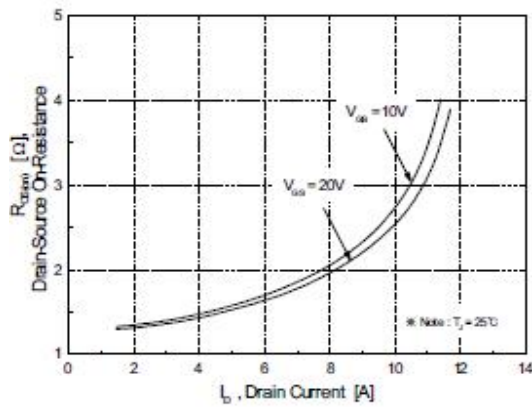


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

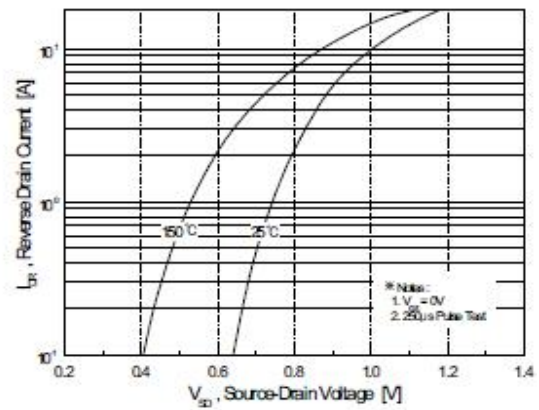


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

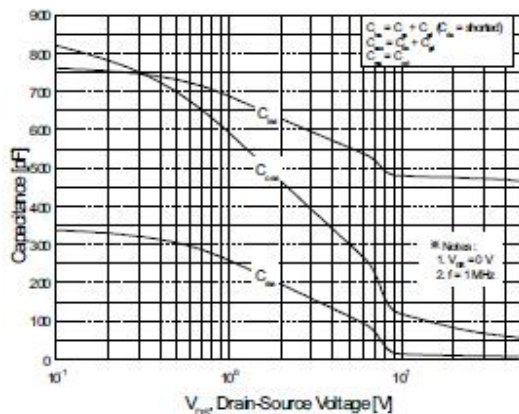


Figure 5. Capacitance Characteristics

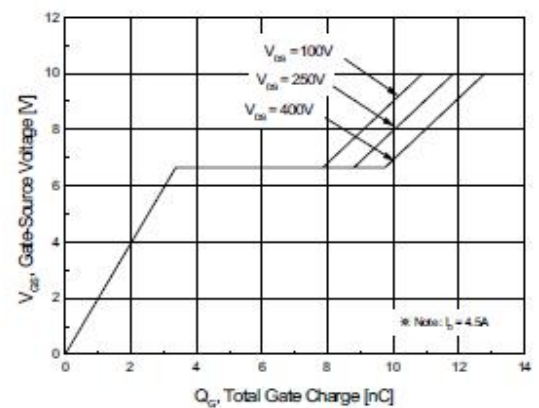


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

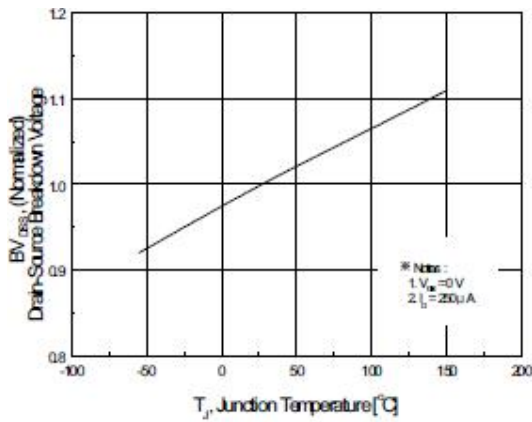


Figure 7. Breakdown Voltage Variation vs. Temperature

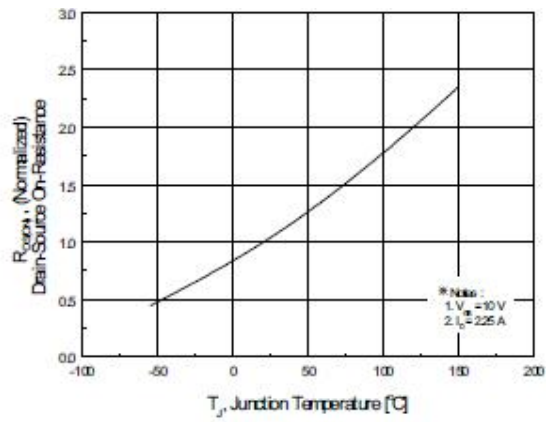


Figure 8. On-Resistance Variation vs. Temperature

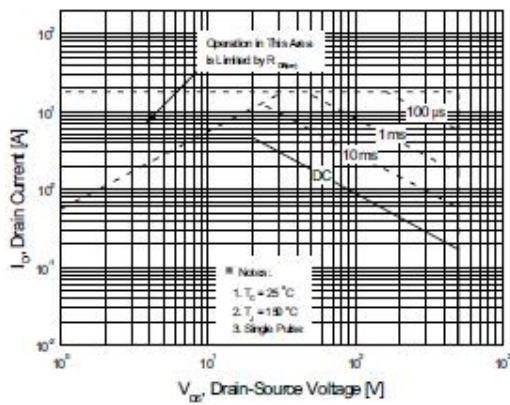


Figure 9. Maximum Safe Operating Area

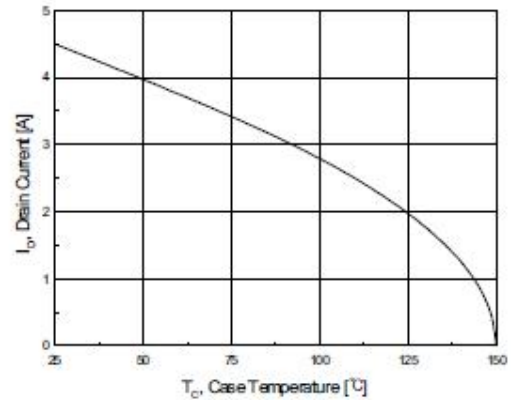


Figure 10. Maximum Drain Current vs. Case Temperature

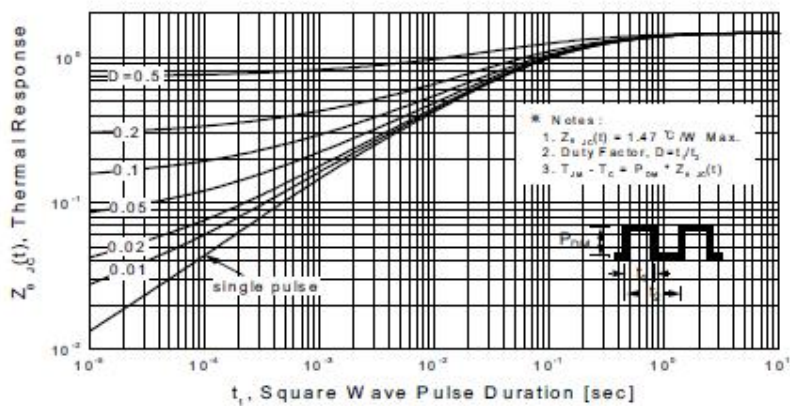
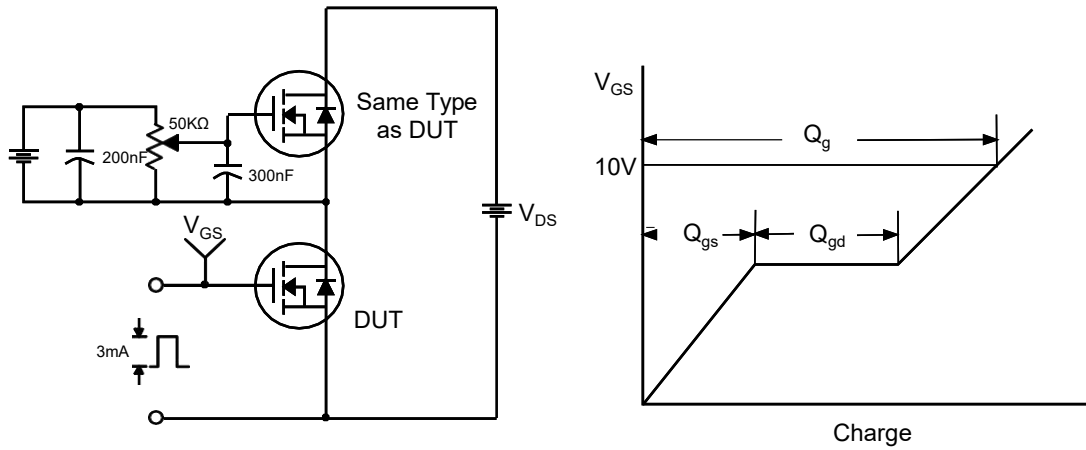
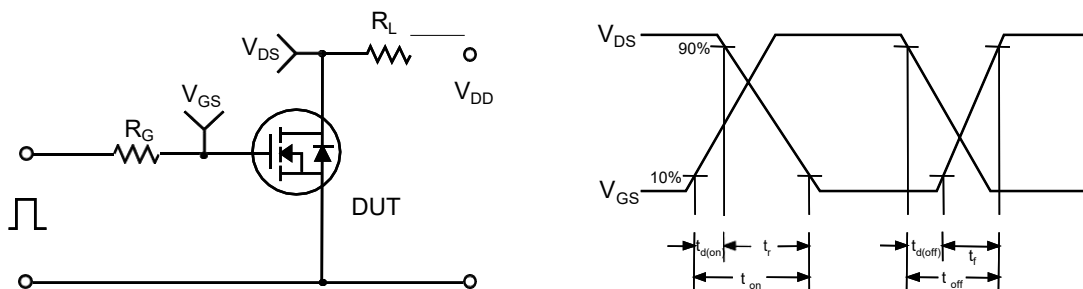


Figure 11. Transient Thermal Response Curve

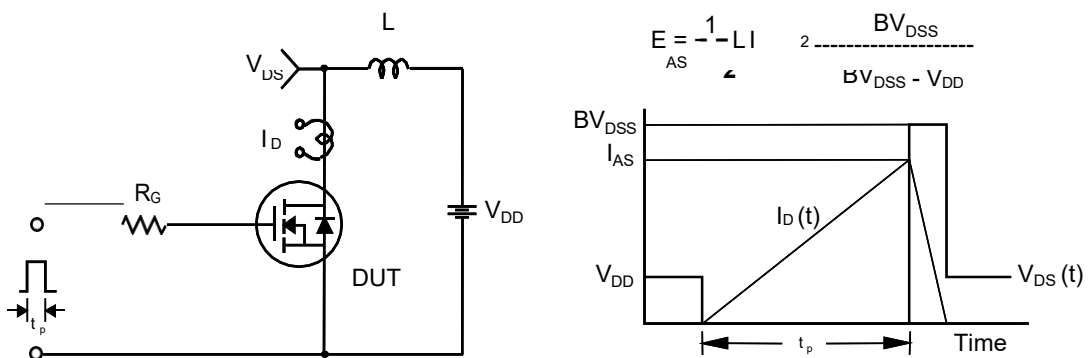
Gate Charge Test Circuit & Waveform



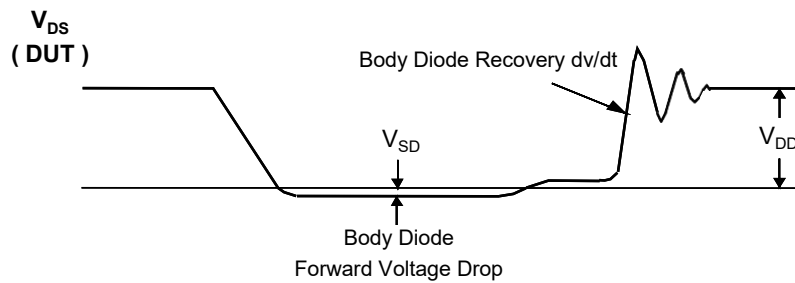
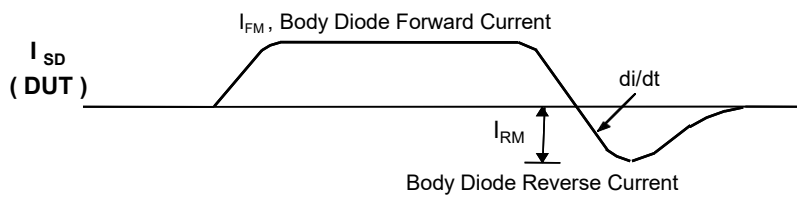
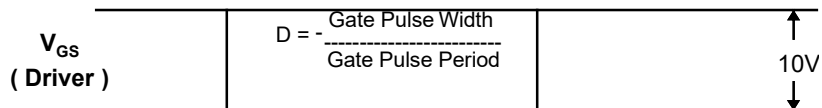
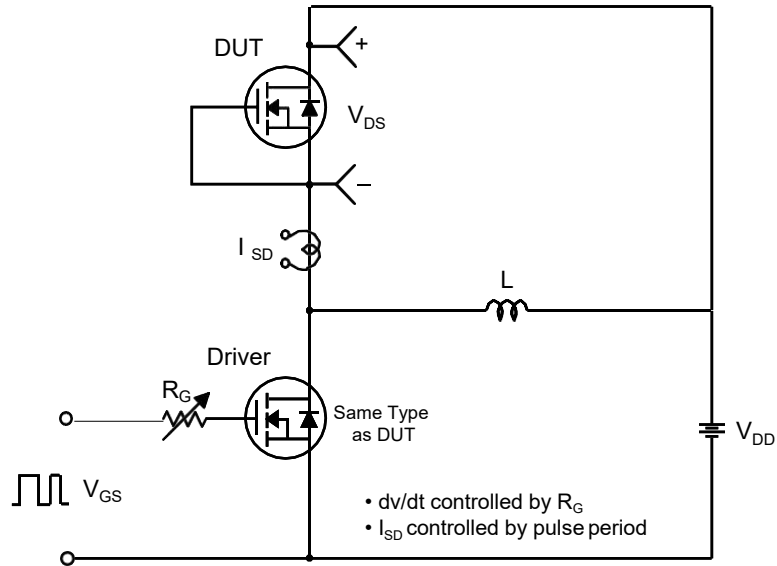
Resistive Switching Test Circuit & Waveforms



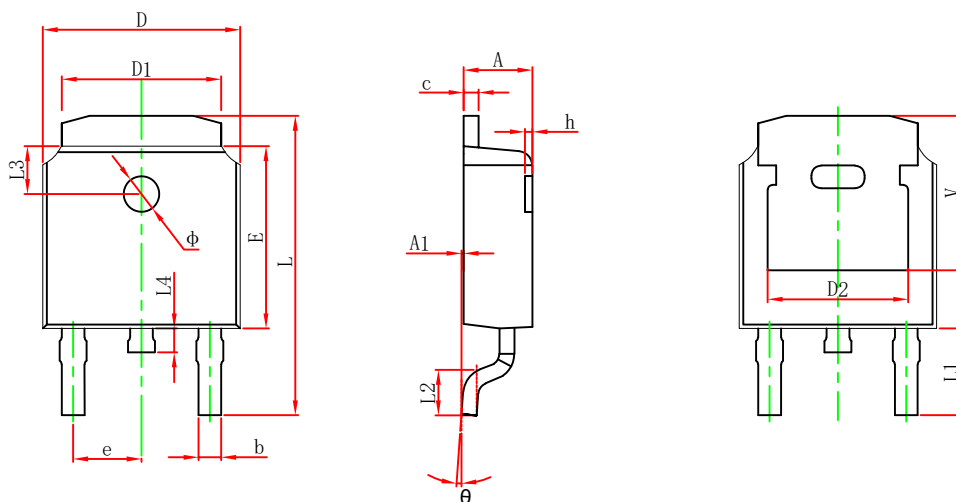
Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms

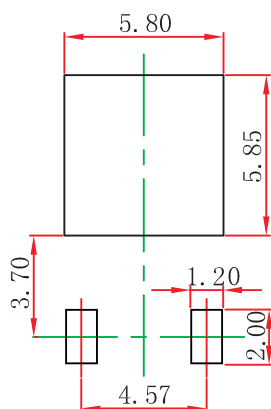


Package Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.700	0.860	0.025	0.030
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.300	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.712	10.312	0.382	0.406
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.250 REF.		0.207 REF.	

TO-252-2L Suggest Pad Layout



NOTE:

1. Controlling dimension: in millimeters.
2. General tolerance: ±0.05mm.
3. The pad layout is for reference purposes only.